

CURRICULUM VITAE SUMMARY

LEMMY L. MEEKISHO

Ph.D., Mechanical Engineering, Carleton University, Ottawa, Canada, 1988

B.Sc., Mechanical Engineering, (With Honors), University of Dar-es-Salaam, Tanzania, 1978

Professional Society Memberships

American Society of Mechanical Engineers (**ASME** International)

American Society for Materials (**ASM** International)

American Society for Engineering Education (**ASEE**)

Employment History

Associate Professor, Department of Mechanical and Materials Engineering, Portland State University, July 1999- present

Associate Professor, Department of Materials Science and Engineering, Oregon Graduate Institute, July 1996-June 1999

Assistant Professor, Department of Materials Science and Engineering, Oregon Graduate Institute, January 1991-June 1996

Research Assistant Professor, Department of Materials Science and Engineering, Oregon Graduate Institute, July 1990-December 1990

Post-Doctoral Research Associate Professor, Department of Materials Science and Engineering, Oregon Graduate Institute, August 1988-June 1990

Selected career highlights

- Distinguished Teaching Award of the Oregon Graduate Institute, 1996.
- Outstanding Teacher Award of Department of Materials Science and Engineering, 1996.
- U.S.A. representative, 3rd International Conference on Quenching and Control of Distortion, Prague, Czech Republic, March 24-26, 1999.
- Keynote lecturer, 7th International Seminar on Heat Treatment and Surface Engineering of Light Alloys, Budapest, Hungary, September 15-17, 1999.
- Co-Chair, 1st International Conference on Thermal Process Modeling and Computer Simulation, Shanghai, P.R. China, March 28-30, 2000.
- Member, Tau Beta Pi, Honor Society, 2000-

- Member, K-16 (Electronic and Photonic Packaging) Committee of the ASME , 2000-
- U.S.A. representative 2nd Intentional Conference on Thermal Process Modeling and Computer Simulation, Nancy France, March 31 – April 2, 2003.
- Associate editor, Volume 7 of International Mechanical Engineering Conference and Exposition (IMECE), Heat Transfer Division Proceedings, 2002
- Session Chair or co-chair for Technical Sessions for IMECE, 2002- present, e.g. Session co-organizer, Technical Session HT-8E, Micro- and Nano-Scale Heat Transfer, IMECE, 2006, Chicago, IL, November 5-10, 2006

Service to the Engineering Society

- Regular reviewer of papers and letters for presentation and/or publication in ASME journals and conference proceedings.
- Reviewer of research and equipment proposals to Foundations from peer academic institutions
- Productive research grantsmanship with research funding from the National Science Foundation (Segmented curriculum), US Navy (Electroslag cladding), US Department of Transportation (Pressure vessel safety), Oregon State Department of Transportation (Bridge weld section metallurgy), US Department of Energy (Welding), Gunderson Inc. (Wheel/rail contact mechanics), Portland General Electric (Finite Element Analysis), Oregon Steel Mills/Gilmore Foundation (Pipe forming characteristics, Materials research).

Service to academia

- 19 years experience in developing and teaching a wide variety of classes both at the undergraduate and graduate levels, in Materials Science and Mechanical Engineering
- Lead supervisor of 5 of PhD dissertations and 10 M.Sc. theses at OGI
- Lead advisor of 10 MSME projects at PSU
- Served on 24 PhD dissertations and M.Sc. theses during my tenure at OGI
- Served on 1 PhD dissertation and 2 MSME and 1 MS-Physics theses at PSU

Book Reviews:

Introduction to Engineering Analysis, by Kirk D. Hagen, ISBN 0-13-016733-9, © 2001, Reviewed for Prentice Hall Publishers, May 2003

Selected Publications

1. Coupled Field Analyses in MEMS with Finite Element Analysis, Ravi Chandra Sikakollu, Lemmy Meekisho, Andres LaRosa, **Journal of Heat Transfer**, vol **127**, January, pp 34-37, 2005
2. Computer-Aided Cooling Curve Analysis using WinProbe, L. Meekisho, B. Hernández-Morales, J.S. Téllez-Martínez , X. Chen, **Int. Journal of Materials and Product Technology**, Vol. 24, No.1-4, pp 155-169, 2005.
3. Interfacial Bond Stress Relationship for Gull wing Solder Joints; L.L. Meekisho, K.N. Owusu, **Journal of Electronic Packaging**, Vol. 126, No. 1, pp 52-56, March, 2004
4. Optimum Gullwing Fillet Solder Joint subjected to Thermomechanical Forces; L.L. Meekisho, K.N. Owusu, **Journal of Electronic Packaging**, Vol. 126, No. 1, March, pp 57-59, 2004
5. Stress Analysis of a Solder Joint with Torsional Eccentricity subjected to Base Excitation, L. Meekisho, K.N. Owusu, **Journal of Mathematical Modelling and Scientific Computing**, Vol. 10 (ISSN 1067-0688), pp193-199, 2000.
6. A Computational Model for the Prediction of Steel Hardenability, M.V. Li, D.V. Niebuhr, L.L. Meekisho, D.G. Atteridge, **Metallurgical and Materials Transactions B**, Vol. 29B, pp.661-671, 1998.
7. Welding Analysis in Moving Coordinates, X. Chen, M. Becker, L. Meekisho, Mathematical Modeling of Weld Phenomena, H. Cerjak (ed), The Institute of Materials, London, UK, pp. 396-410, 1997.
8. Finite Element Analysis in Moving Coordinates, X. Chen, M. Becker, L. Meekisho, ASME-HTD 384, L. Clarksean, R. Hogan, *et al* (eds). pp 91-99, 1997.
9. Generalized Approximations of Wheel-Rail Creep Forces and Contact Patch Frictional work Using Neural Network Simulation, R.F. Harder, L.L. Meekisho, J.Jones V. Rhoades, **2nd International Mini Conference on Contact Mechanics and wear of Rail/wheel Systems**, Budapest, Hungary, July 29-31, 1996.
10. Analysis of Stress Singular Fields at a Bimaterial Wedge Corner, S. Ding, L. Meekisho, M. Kumosa, **Engineering Fracture Mechanics**, Vol. 49, No.4, pp 569-585, 1994

Selected Invited Presentations

1. Computer Modeling, an Important Tool in Materials Processing, L. Meekisho, Invited Keynote Paper presented at the 1st International Conference on Thermal Process Modeling and Computer Simulation, ASM/SJTU/CME, Shanghai, China, March 28-30, 2000.

2. Heat Treatment Process Modeling; Challenges and Opportunities, L. Meekisho, X. Chen, Invited Keynote Paper presented at the 7th International Seminar on Heat Treatment and Surface Engineering of Light Alloys, IFHT/GTE, Budapest Hungary, September 15-17, 1999.
3. Modeling of the coupled Thermal-Fluid interaction Phenomena with Applications in Electronic Packaging L. Meekisho, Given at Intel Corporation, Aloha Campus, May 1, 1996.
4. Multiple Cracking Phenomena in Energy Absorbing Glasscloth Epoxy Tubes, M. Kumosa and L. L. Meekisho, International Conference on Mixed-Mode Fracture and Fatigue, Vienna, Austria, July 15-17, 1991.